

ABSTRACT

MOLDING SYSTEM FOR APPLYING A UNIFORM CLAMPING PRESSURE ONTO A SUBSTRATE

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A molding system for encapsulating electronic devices mounted on a substrate, the molding system comprising a first mold chase with a first mold chase surface and a second mold chase with a second mold chase surface opposite to the first mold chase surface, the first and second mold chase surfaces being operative to clamp onto the
10 substrate and to apply a clamping pressure thereto. The molding system further comprises a first sensor located at a first position for determining a first relative distance between the substrate and a mold chase facing the substrate at the first position, and a second sensor located at a second position for determining a second relative distance
15 between the substrate and a mold chase facing the substrate at the second position. The molding system also comprises a first actuator located adjacent to the first position and a second actuator located adjacent to the second position, wherein the first and second actuators are operative to adjust the first relative distance with respect to the second relative distance for applying a uniform clamping pressure onto the substrate.

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[FIG. 4A]